

## Materials Declaration

<b>Package</b>	LFCSP
<b>Body Size</b>	3 X 3 X 0.85
<b>LeadCount</b>	16
<b>Option</b>	Halide-free, Pb-free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.9	5.77 E-03	331321
Epoxy & Phenol Resin	12.8	8.48 E-04	48720
Carbon black	0.3	2.06 E-05	1182
Subtotal		6.64 E-03	381223

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	8.91 E-03	511859
Fe	2.35	2.15 E-04	12351
Zn	0.12	1.10 E-05	632
P	0.03	2.74 E-06	157
		9.14 E-03	525000

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	1.78 E-04	10226

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	1.11 E-04	6377

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	1.99 E-04	11432

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	9.71 E-04	55782

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	73.40	1.27 E-04	7312
Epoxy Resin	18.35	3.18 E-05	1828
Metal oxide	2.75	4.77 E-06	274
Curing and hardening agent	2.75	4.77 E-06	274
Gamma Butyrolactone	2.75	4.77 E-06	274
Subtotal		1.73 E-04	9961

Molding Compound		
Item	PPM	Method
Pb	Not Detected	Draft IEC 62321, ICP-OES.
Cd	Not Detected	Draft IEC 62321, ICP-OES.
Hg	Not Detected	Draft IEC 62321, ICP-OES.
Cr+6	Not Detected	Draft IEC 62321, UV-VIS.
PBB	Not Detected	Draft IEC 62321, GC-MSD.
PBDE	Not Detected	Draft IEC 62321, GC-MSD.

Die Attach Paste		
Item	PPM	Method
Pb	Not Detected	Draft IEC 62321, ICP-OES.
Cd	Not Detected	Draft IEC 62321, ICP-OES.
Hg	Not Detected	Draft IEC 62321, ICP-OES.
Cr+6	Not Detected	Draft IEC 62321, UV-VIS.
PBB	Not Detected	Draft IEC 62321, GC-MSD.
PBDE	Not Detected	Draft IEC 62321, GC-MSD.

### Package Totals

Weight (g)	PPM
1.74 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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<b>Package</b>	LFCSP
<b>Body Size</b>	3 X 3 X 0.85
<b>LeadCount</b>	16
<b>Option</b>	Halide-free, Sn/Pb

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.9	5.77 E-03	331330
Epoxy & Phenol Resin	12.8	8.48 E-04	48722
Carbon black	0.3	2.06 E-05	1182
Subtotal		6.64 E-03	381234

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	8.91 E-03	511874
Fe	2.35	2.15 E-04	12352
Zn	0.12	1.10 E-05	632
P	0.03	2.74 E-06	157
Subtotal		9.14 E-03	525015

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	1.78 E-04	10226

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	9.39 E-05	5394
Pb	15	1.66 E-05	954
Subtotal		1.11 E-04	6348

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	1.99 E-04	11432

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	9.71 E-04	55783

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	73.40	1.27 E-04	7312
Epoxy Resin	18.35	3.18 E-05	1828
Metal oxide	2.75	4.77 E-06	274
Curing and hardening agent	2.75	4.77 E-06	274
Gamma Butyrolactone	2.75	4.77 E-06	274
Subtotal		1.73 E-04	9962

Package Totals		
Weight (g)	PPM	
1.74 E-02	1000000	

Molding Compound		
Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Die Attach Paste		
Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

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